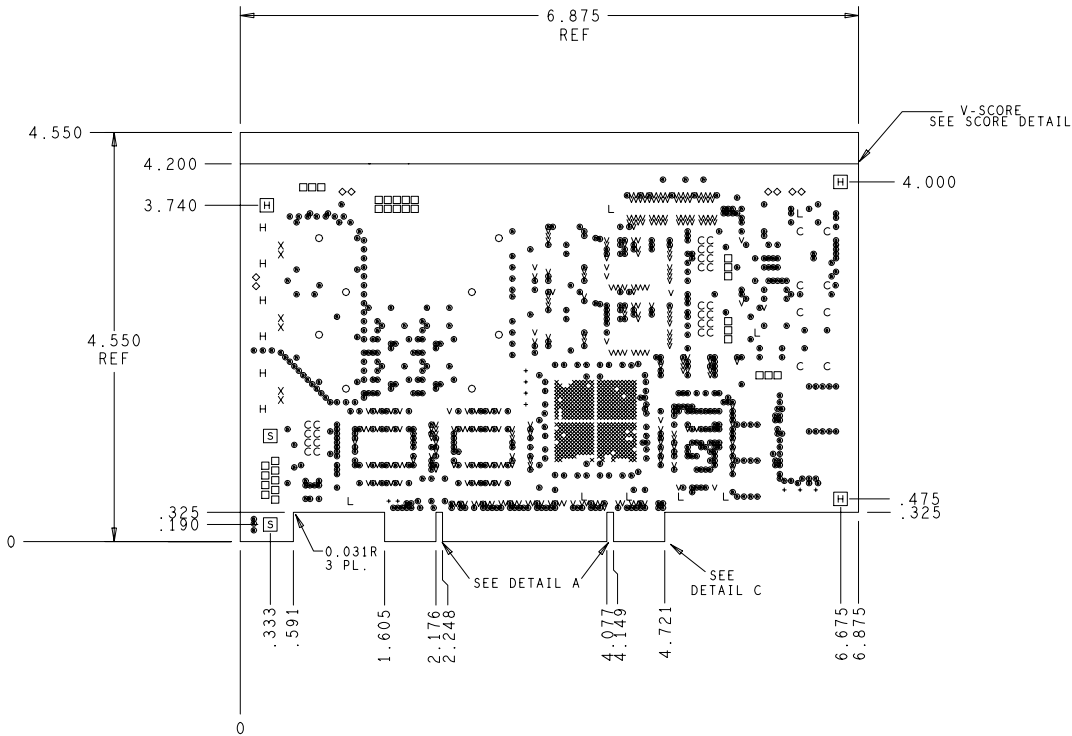
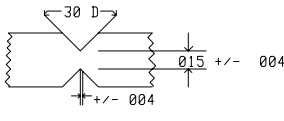
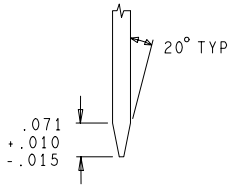
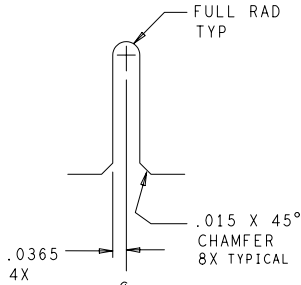


REVISIONS			
REV	DESCRIPTION	DATE	APPROVED

DRILL CHART			
ALL UNITS ARE IN INCHES			
FIGURE	SIZE	PLATED	QTY
x	0.01	PLATED	440
v	0.012	PLATED	252
+	0.013	PLATED	9
•	0.0135	PLATED	691
c	0.03	PLATED	32
L	0.032	PLATED	8
x	0.035	PLATED	6
□	0.042	PLATED	31
◇	0.043	PLATED	8
o	0.06	PLATED	8
H	0.079	PLATED	6
[H]	0.125	PLATED	3
[S]	0.125	NON-PLATED	2

+ .000/- .010
+ .000/- .012
+ .000/- .013
+ .000/- .0135

- NOTES:
- PRIMARY / COMPONENT SIDE SHOWN.
 - LAYER ORIENTATION: SEE LAYER DETAIL.
 - MATERIAL: TETRA- OR MULTI- FUNCTIONAL FR-4 LAMINATES AND PREPREGS PER MIL-P-13949. MINIMUM GLASS TRANSITION TEMPERATURE (Tg) OF 170 DEGREE CENTIGRADE REQUIRED. PREPREG & CORE DIELECTRICS MUST BE A MINIMUM 2 PLY.
 - THICKNESS: 0.062" +/- 0.006" (FINISHED)
 - PLATING:
 - 1/2 OZ. PLATED TO 1.5 OZ. ON OUTER LAYERS
 - 1/2 OZ ON INNER SIGNAL LAYERS.
 - 1 OZ. ON PLANE LAYERS (NO PLATE)
 - PLATED THROUGH HOLES SHALL HAVE A MINIMUM AVERAGE COPPER THICKNESS OF .001" WITH AN ABSOLUTE MINIMUM THICKNESS OF .0008", AS MEASURED IN MIL-P-55110.
 - FINGER CONNECTIONS TO BE ELECTROLYTIC HARD GOLD (.50-100 MICROINCH) OVER LOW STRESS ELECTROLYTIC NICKEL (200 MICROINCH) PER IPC-D-275, TABLE 3-8 CLASS 2.
 - FINISH: NICKEL GOLD IMMERSION AFTER SOLDER MASK APPLICATION.
 - ANNULAR RING: .002" MINIMUM FOR EXTERNAL ANNULAR RING. .001" MINIMUM FOR INTERNAL ANNULAR RING. TANGENCY IS ACCEPTABLE ON .010" DIA. HOLES.
 - SOLDER MASK: LIQUID PHOTO IMAGEABLE;
SOLDER MASK OVER BARE COPPER BOTH SIDES.
SOLDER MASK REGISTRATION TO BE WITHIN +/- .003" OF ITS RESPECTIVE CIRCUIT LAYERS, AND NO MASK TO APPEAR ON PADS.
 - BOW AND TWIST: MAXIMUM OF .010 INCH / INCH FOR THROUGH HOLE BOARDS.
MAXIMUM OF .0075 INCH / INCH FOR SURFACE MOUNT BOARDS.
 - SILKSCREEN: WHITE NON-CONDUCTIVE INK. NO INK TO APPEAR ON COMPONENT PADS. LINES TO BE .006" MINIMUM.
 - PCB: NOMINAL CONDUCTOR WIDTHS ON FINISHED BOARD TO BE WITHIN +/-15%, OR +/-1 MIL, WHICHEVER IS LESS OF ARTWORK AS DEFINED ON GERBERS AND SUPPLIED APERTURE WIDTH.
 - ELECTRICAL TEST: FINISHED PCB TO BE SUBJECT TO 100% CONTINUITY AND ISOLATION ELECTRICAL TEST. TEST FIXTURES TO BE GENERATED FROM IPC-D-356 FORMATTED NET LIST DATA, CROSS-REFERENCED TO GERBER EXTRACTED NET LIST DATA. VENDOR TO TEST IMPEDANCE ON A COUPON.
 - HOLE CHART: UNLESS OTHERWISE SPECIFIED, ALL TOLERANCES ARE +/- .003"
 - SPACING: MINIMUM FINISHED CONDUCTOR SPACING TO BE 5 MILS
 - SPECIFICATION: UNLESS OTHERWISE SPECIFIED, FAB OF THIS PCB SHALL BE IN CONFORMANCE WITH THE FOLLOWING.
IPC-6011 CLASS 2 (GENERIC)
IPC-6012 CLASS 2 (RIGID)
 - FLAME CLASS: UL 94V-0 AND MUST MEET REQUIREMENTS OF UL796
 - MOT: MANUFACTURER MUST BE UL RECOGNIZED TO PRODUCE THIS PRODUCT SUCH THAT IT MEET 130 deg C MAXIMUM OPERATING TEMPERATURE
 - MARKINGS: THE FOLLOWING MUST BE MARKED OR ETCHED ON SIDE OF 2 OF PCB IN AREA FREE OF COMPONENT COVERING:
DATECODE (YYWW), UL RECOGNIZED VENDOR ID, UL TYPE DESIGNATION,
AND/OR MARKING WHICH REFLECT THE SPECIFIED FLAME CLASS AND MAXIMUM OPERATING TEMPERATURE RATINGS.



PRIMARY SIDE	LAYER 1		1/2 OZ
INTERNAL SIGNAL 1	LAYER 2		1/2 OZ
GROUND PLANE	LAYER 3		1 OZ
POWER PLANE +2.5/+5	LAYER 4		1 OZ
POWER PLANE +3.3	LAYER 5		1 OZ
GROUND PLANE	LAYER 6		1 OZ
INTERNAL SIGNAL 2	LAYER 7		1/2 OZ
SECONDARY SIDE	LAYER 8		1/2 OZ

LAYER DETAIL
CONSTRUCTION LAMINATE THICKNESS
AT VENDORS' DISCRETION

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TOLERANCES (UNLESS OTHERWISE NOTED)			
.XX	+/- .01	FRACTIONS	ANG
.XXX	+/- .005	+/- 1/64	1/2°
DRAWN	FREEDOM CAD	01/26/04	TITLE FABRICATION DRAWING RVP8/Tx
CHECKED			
ENGR APPD			
ENGR APPD			
PROJECT MANAGER			SIZE D
			DRAWING NUMBER RVP8/TX
			REV D
SCALE 1/1 SHEET 1 OF 1 FREEDOMCAD#581001F1 LEVEL			